Docket No.

240586US2/hc

IN THE UNITED STATE SPATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Takashi IPPOSHI

SERIAL NO: FILED: 10/623,557

July 22, 2003

GAU:

EXAMINER:

FOR:

SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.

☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

MILD CIES
Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.

☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of
this statement.

No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

■ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Joseph A Acar

Marvin J. Spivak

Registration No. 24,913

Joseph A. Scafetta, Jr. Registration No. 26,803

Customer Number

22850

Tel. (703) 413-3000 Fax. (703) 413-2220 (OSMMN 05/03) DOCKET NO.: 240586US2/hc

IN THE UNITED STATES LATER AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Takashi IPPOSHI

SERIAL NO: 10/623,557

GROUP:

FILED:

July 22, 2003

EXAMINER:

FOR:

SEMICONDUCTOR DEVICE

STATEMENT OF RELEVANCY

All of the references on Form 1449 are discussed in the specification.

Form PTO 1449 (Modified)		U.S. DEPARTMENT	OF COMMERCE	ATTY DOCKET NO.	SERIAL NO.					
(Modified)		PATENT AND TRAD		240586US2	10/623,557					
		(O)	PEVC	APPLICANT						
LIST OF	REFE	RENCES CITED BY AP		Takashi IPPOSHI						
		Tan)	2 2 2003	FILING DATE		GROUP				
		_	Š,	July 22, 2003						
U.S. PATENT DOCUMENTS										
EXAMINER		DOCOMENT	DATE	NAME	CLASS	SUB		ILING DATE		
INITIAL	AA	NUMBER				CLASS IF APPROPRIATE				
	AB				 					
	AC							··-		
	AD									
	AE				1					
	AF		-		<u> </u>					
	AG				<u> </u>					
	АН		· · · · · · · · · · · · · · · · · · ·							
	Al									
	AJ									
	AK									
	AL									
	AM									
	AN									
			FO	REIGN PATENT DOCUMENTS						
	DOCUMENT DATE			COUNTRY		TRANSLATION				
	NOMBER		LADAN (com LICCN 00/020 200)				NO			
	AO AP	2002-134374 7-335511	05/10/2002 12/22/1995	JAPAN (corr. USSN 09/930,202)				X		
	AQ	7-333371	12/22/1993	JAPAN (with English extract)				X		
	AR									
	AS							·		
	AT									
	AU									
	AV									
		OTHER RE	FERENCES (Including Author, Title, Date, Pertinen	t Pages e	tc)	1			
			·	SOI Conference, pages 131-132, "BUL			IDI E A	19um COL CMOS		
	AW	TECHNOLOGY USING	G BODY-FIXE	D PARTIAL TRENCH ISOLATION (PTI)	", October	1999	IBLE V.	Toprii SOI-CMOS		
	AX	S. MAEDA, et al., IEDM, pages 129-132, "SUPPRESSION OF DELAY TIME INSTABILITY ON FREQUENCY USING FIELD SHIELD ISOLATION TECHNOLOGY FOR DEEP SUB-MICRON SOI CIRCUITS", 1996								
	AY	L-J. HUANG, et al., Symposium on VLSI Technology Digest of Technical Papers, pages 57-58, "CARRIER MOBILITY AY ENHANCEMENT IN STRAINED Si-On-INSULATOR FABRICATED BY WAFER BONDING", 2001								
	AZ Additional References sheet(s) attached									
Examiner Date Considered										
				citation is in conformance with MPEP 6 with next communication to applicant.	09; Draw li	ne through	citation	if not in		
Jonnonnance	4114 116	sonsacrea, moduce o	Py or una lott	THE HOLE COMMITTATION OF THE APPRICANT.						